



3D Packaging & Integration Taiwan TC Chapter Meeting Summary and Minutes

Taiwan Summer Standards Meeting 2018

Tuesday, September 25, 2018, 14:30 – 16:00

11F-2, No. 1, Taiyuan 1st Street, Zhubei City, Hsinchu County, Taiwan

TC Chapter Announcements

Next TC Chapter Meeting

Tuesday, December 18 2018, 14:30 – 16:00

11F-2, No. 1, Taiyuan 1st Street, Zhubei City, Hsinchu County, Taiwan

Table 1 Meeting Attendees

Co-Chairs: Roger Hwang (ASE)

SEMI Staff: Dean Chang

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
CMPUGTW	Kong	LC	KYEC	Chen	Wendy
ITRI	Lin	Chien-chung	KYEC	Hsu	Bernard
ITRI	Chen	Shang-Chun	KYEC	Tsai	Ming Chin
ITRI	Chang	Hsiang- Hung	Chung King	Yang	Ian
ITRI	Ou Yang	Tsung Yu	Acteon NEXT	Shoji	Komatsu

Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

Table 3 Committee Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
6405	Reapproval of SEMI 3D7-0913, GUIDE FOR ALIGNMENT MARK FOR 3DS-IC PROCESS	Passed , as ballot
6411	Line Item Revision of SEMI 3D6-0913, GUIDE FOR CMP AND MICRO-BUMP PROCESSES FOR FRONTSIDE THROUGH SILICON VIA (TSV) INTEGRATION	Passed , as ballot

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.



Table 5 Activities Approved by the GCS between meetings of the TC Chapter

#	Type	SC/TF/WG	Details
None			

Table 6 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	Type	SC/TF/WG	Details
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Table 7 Authorized Ballots

#	When	TF	Details

Table 8 SNARF(s) Granted a One-Year Extension

#	TF	Title	Expiration Date
None			

Table 9 SNARF(s) Abolished

#	TF	Title
None		

Table 10 Standard(s) to receive Inactive Status

Standard Designation	Title
None	

Table 11 New Action Items

Item #	Assigned to	Details
1	Dean Chang	Call for member to join the I&C TC / Backend Factory Integration Task Force telephone meeting

Table 12 Previous Meeting Action Items

Item #	Assigned to	Details
1	Andy Tuan	Invite Corning to join the 3D P&I TC meeting.
2	Dean Chang	Shang-Chun Chen and Dean Chang contact to CAST.
3	Dean Chang	Invite 3D P&I TC members to join the I&C TF telephone meeting on May 18.



1 Welcome, Reminders, and Introductions

Committee Co-Chair Roger Hwang (ASE) called the meeting to order at 14:30. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance reviewed. Attendees introduced themselves.

Attachment: [Meeting Reminder 2018](#)

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion: Approve previous meeting minute
By / 2nd: Shang-Chun Chen (ITRI) / Hsiang- Hung Chang(ITRI)
Discussion: After review, all TC members agreed to approve it
Vote: 10-0 in favor, Motion passed

Attachment: [20180510 3D Meeting Minutes](#)

3 Liaison Reports

3.1 3D Packaging & Integration North America TC Chapter

Dean Chang (SEMI) reported for the 3D Packaging & Integration North America TC Chapter. Of note:

- Next TC Meeting will be held on November 8, 2018
- Authorized Ballots
 - Cycle 7-18
 - Doc (6075, 6175, 6332, 6412)

Attachment: [NA 3DP&I Liaison Report Jul2018 v2](#)

3.2 3D Packaging & Integration Japan TC Chapter

Dean Chang (SEMI) reported for the 3D Packaging & Integration Japan TC Chapter. Of note:

- Next TC Meeting will be held on October 15, 2018
- Leadership Changes: Hideki Suzuki stepped down
- Ballot Results: Doc6352&Doc6353 are passed

Attachment: [20180701 3DP&I-Japan Liaison v1.0](#)

3.3 SEMI Staff Report

Dean Chang (SEMI) gave the SEMI Staff Report. Of note:

- SEMI Global 2018 Calendar of Events
- 2018 Critical Dates for SEMI Standards Ballots
- Cycle 6-18 ballot results
- S2 training seminar

Attachment:

- [3D P&I TC Staff Report 20180925](#)

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed in detail in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document provided under each ballot review section below.

Doc #	Document Title	TC Chapter Action
6405	Reapproval of SEMI 3D7- 0913, Guide For Alignment Mark For 3DS IC Process	Passed, as balloted
6411	Reapproval of SEMI 3D7-0913, Guide For Alignment Mark For 3DS IC Process	Passed, as balloted

5 Subcommittee and Task Force Reports

5.1 Testing Task Force

Shang-Chun Chen (ITRI) reported for the Testing Task Force. This report contained information on:

Attachment: [TF Leader report 20170925 v1](#)

5.2 Middle End Process Task Force

None

6 Old Business

- 6.1 Andy Tuan invite Corning to join the 3D P&I TC meeting.
- 6.2 Dean Chang and Shang-Chun Chen contact to CAST.
- 6.3 Dean Chang invite 3D P&I TC members to join the I&C TF telephone meeting on May 18.

7 New Business

- 7.1 Call for member to join the I&C TC / Backend Factory Integration Task Force telephone meeting.

8 Next Meeting and Adjournment

The next meeting scheduled for December 18, 2018 at SEMI Taiwan Office. See <http://www.semi.org/standards-events> for the current list of events.

Adjournment was at 16:00.

Respectfully submitted by:

Dean Chang

Senior Executive Consultant



SEMI Taiwan

Phone: 886-3-560-1777 #801

Email: dchang@semi.org

Minutes tentatively approved by:

Wendy Chen (KYEC), Co-chair	2018/12/18
Chien-chung Lin (ITRI), Co-chair	2018/12/18

Table 13 Index of Available Attachments#1

<i>Title</i>	<i>Title</i>
1_ Meeting Reminder_2018	3.2_20180701_3DP&I-Japan_Liaison_v1.0
2_ 20180510_3D Meeting Minutes	3.3_3D P&I TC Staff Report_20180925
3.1_ NA 3DP&I Liaison Report Jul2018 v2	5.1_ TF Leader report_20170925_v1

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.